

SML10G3-TR

Hi-Eff Green

Surface Mount LED

3.0 × 3.0 × 1.0mm Chip LED

140° viewing angle

DWG BY:
BL / GP
09-12-06

CHK BY:
PL
09-11-07

QA:

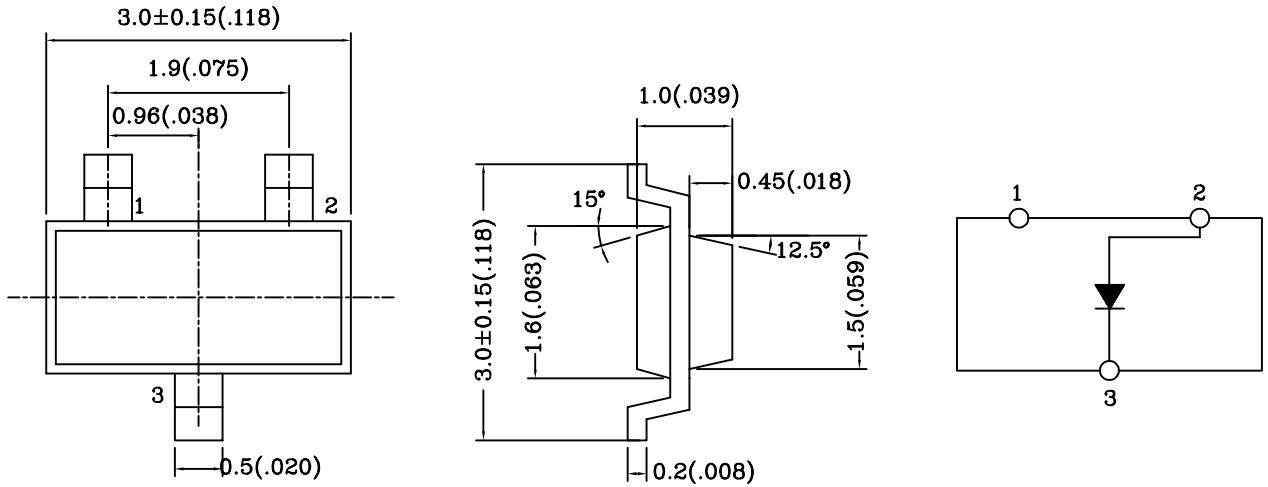
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MFG:

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REVISION LTR: -
09-11-07

● PACKAGE DIMENSIONS



- NOTES: 1.All dimensions are in millimeters (inches).
 2.Tolerance is ± 0.10 mm (0.004) unless otherwise specified.
 3.Specifications are subject to change without notice.
 4.Condition for IFp is pulse of 1/10 duty and 0.1msec width.

● Absolute Maximum Ratings(Ta=25°C)

| Parameter | Symbol | Rating | Unit |
|--------------------------|-----------------|-------------|------|
| Power Dissipation | P _d | 100 | mW |
| Forward Current | I _F | 30 | mA |
| Peak Forward Current * 1 | I _{FP} | 150 | mA |
| Reverse Volage | V _R | 5 | V |
| Operating Temperature | Topr | -25°C ~80°C | - |
| Storage Temperature | Tstg | -30°C ~85°C | - |
| Soldering Temperature | Tsol | See Page6 | - |

Remark : Viewing angle is the Off-axis angle at which the luminous intensity is half the axial luminous intensity.

● **Electrical and optical characteristics(Ta=25°C)**

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------|------------------|------------|------|------|------|------------|
| Forward Voltage | V_F | $I_F=20mA$ | - | 2.2 | 2.6 | V |
| Luminous Intensity | I_v | $I_F=20mA$ | - | 10 | - | mcd |
| Reverse Current | I_R | $V_R=5V$ | - | - | 100 | μA |
| Peak Wave Length | λ_p | $I_F=20mA$ | 565 | 566 | 568 | nm |
| Dominant Wave Length | λ_d | $I_F=20mA$ | 570 | 572 | 573 | nm |
| Spectral Line Half-width | $\Delta \lambda$ | $I_F=20mA$ | - | 30 | - | nm |
| Viewing Angle | $2\theta_{1/2}$ | $I_F=20mA$ | - | 140 | - | deg |
| Radiant Intensity | | $I_F=20mA$ | - | - | - | $\mu W/sr$ |
| Chromaticity Coordinates | X | $I_F=20mA$ | - | 0.46 | - | |
| | Y | | - | 0.54 | - | |

● **Typical Electro-Optical Characteristics Curves**

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

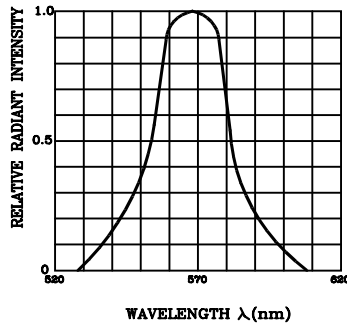


Fig.2 FORWARD CURRENT DERATING CURVE

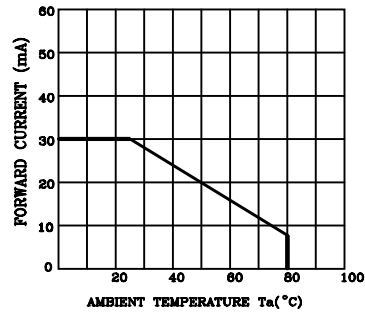


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

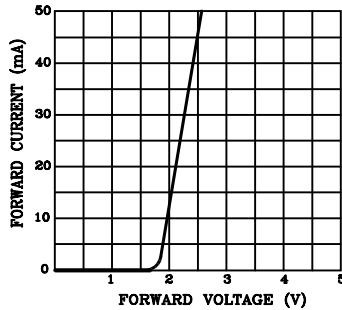


Fig.4 RELATIVE LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

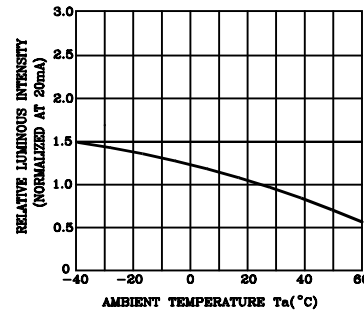


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

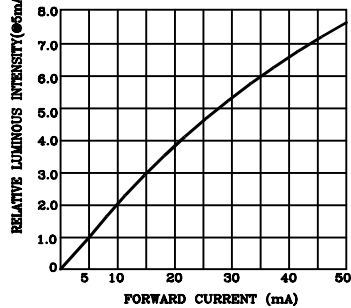
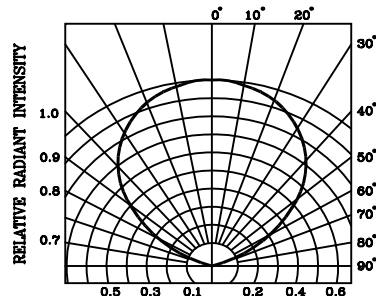
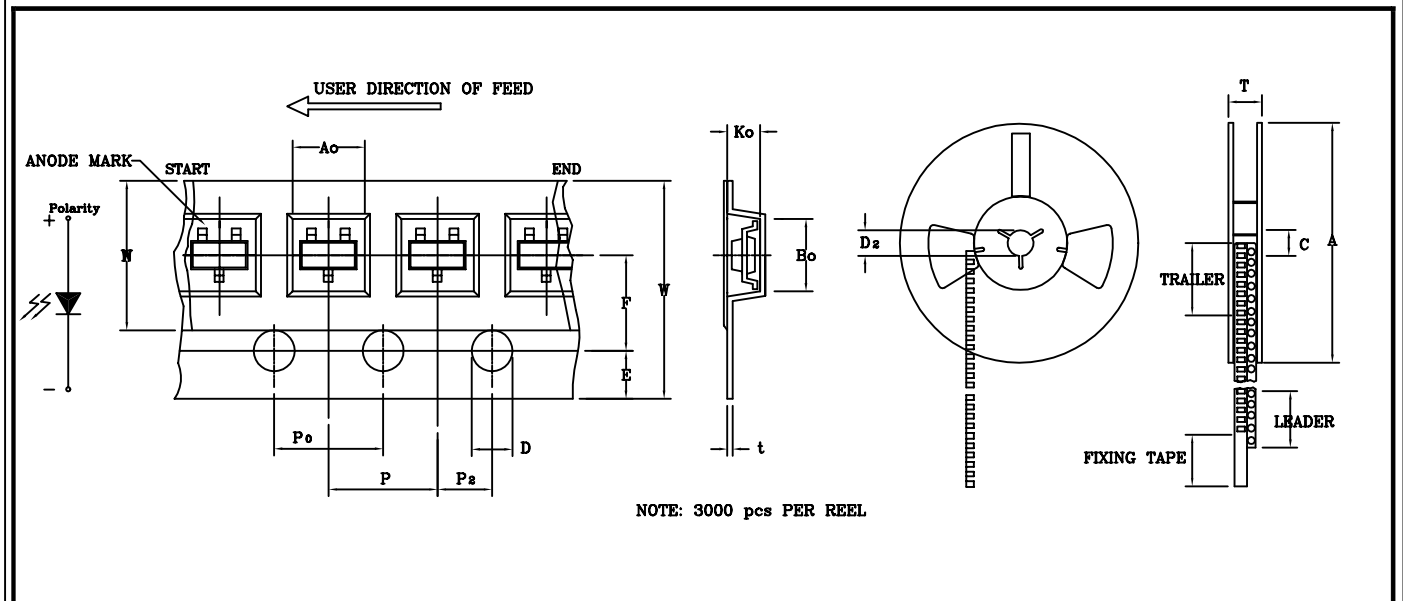


Fig.6 RADIATION DIAGRAM



| ITEM | SYMBOL | SPECIFICATION | | | |
|--|----------------|---------------|-------|---------|-------|
| | | Minimum | | Maximum | |
| | | mm | inch | mm | inch |
| Tape Feed Hole Diameter (DIA) | D | 1.50 | 0.059 | 1.60 | 0.063 |
| Feed Hole Location | E | 1.65 | 0.064 | 1.85 | 0.073 |
| Centers Line Dimensions Length Direction | F | 3.45 | 0.135 | 3.55 | 0.139 |
| Compartment Depth | K ₀ | 1.40 | 0.049 | 1.60 | 0.057 |
| Compartment Pitch | P | 3.90 | 0.153 | 4.10 | 0.161 |
| Sprocket Hole Diameter | P ₀ | 3.90 | 0.153 | 4.10 | 0.161 |
| Centers Line Dimensions Length Direction | P ₂ | 1.95 | 0.076 | 2.05 | 0.080 |
| Carrier Tape Thickness | t | — | — | 0.30 | 0.012 |
| Carrier Tape Width | W | 7.70 | 0.303 | 8.30 | 0.326 |
| Flange Diameter | A | 176.0 | 6.928 | 180.0 | 7.087 |
| Hub Spindle Hole | C | 12.50 | 0.492 | 13.50 | 0.531 |
| Hub Diameter | D ₂ | 20.10 | 0.791 | 20.30 | 0.799 |
| Fixing Tape Width | N | 59.00 | 2.322 | 61.00 | 2.402 |
| Flange Space Between Flanges | T | 14.30 | 0.563 | 14.50 | 0.571 |
| Compartment Length | A ₀ | 3.10 | 0.122 | 3.20 | 0.130 |
| Compartment Width | B ₀ | 3.10 | 0.122 | 3.20 | 0.130 |



| Classification | Test Item | Reference Standard | Test Conditions | Result |
|--------------------|--|---|--|--------|
| Endurance Test | Operation Life | MIL-STD-750:1026 MIL-STD-883:1005 JIS C 7021 :B-1 | Connect with a power If=20mA Ta=Under room temperature Test time=1,000hrs | 0/20 |
| | High Temperature High Humidity Storage | MIL-STD-202:103B JIS C 7021 :B-11 | Ta=+65°C±5°C RH=90%-95% Test time=1,000hrs | 0/20 |
| | High Temperature Storage | MIL-STD-883:1008 JIS C 7021 :B-10 | High Ta=+85°C±5°C Test time=1,000hrs | 0/20 |
| | Low Temperature Storage | JIS-C-7021 :B-12 | Low Ta=-35°C±5°C Test time=1,000hrs | 0/20 |
| Environmental Test | Temperature Cycling | MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS C 7021 :A-4 | -35°C ~ +25°C ~ +85°C ~ +25°C 60min 20min 60min 20min Test Time=5cycle | 0/20 |
| | Thermal Shock | MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011 | +85°C±5°C ~ -35°C±5°C 20min 20min Test Time=10cycle | 0/20 |
| | Solder Resistance | MIL-STD-202:201A MIL-STD-750:2031 JIS C 7021 :A-1 | Preheating : 140°C-160°C, within 2 minutes. Operation heating : 235°C (Max.), within 10seconds.(Max.) | 0/20 |

JUDGMENT CRITERIA OF FAILURE FOR THE RELIABILITY

| Measuring items | Symbol | Measuring conditions | Judgement criteria for failure |
|--------------------|------------------------|----------------------|--------------------------------|
| Forward voltage | V _F (V) | If=20mA | Over U _x 1.2 |
| Reverse current | I _r (uA) | V _r =5V | Over U _x 2 |
| Luminous intensity | I _v (mcd) | If=20mA | Below S _X 0.5 |

Note: 1.U means the upper limit of specified characteristics. S means initial value.
 2.Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.

1. SOLDERING :

● **Manual Of Soldering**

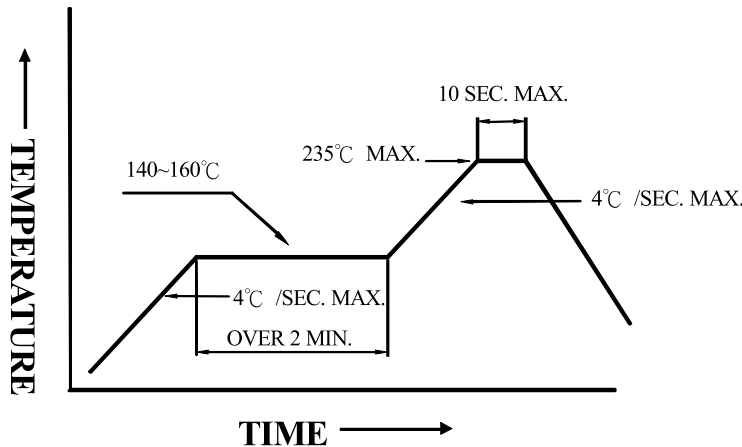
The temperature of the iron tip should not be higher than 300°C (572°F) and Soldering within 3 seconds per solder-land is to be observed.

● **Reflow Soldering**

Preheating : 140°C~160°C ±5°C, within 2 minutes.

Operation heating : 235°C (MAX.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).

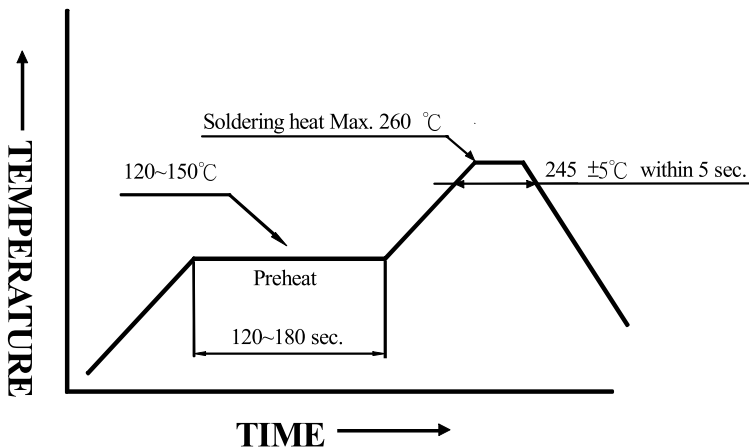


● **DIP soldering (Wave Soldering)**

Preheating : 120°C~150°C, within 120~180 sec.

Operation heating : 245°C ±5°C within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).



2. Handling :

Care must be taken not to cause to the epoxy resin portion of LEDs while it is exposed to high temperature.

Care must be taken not rub the epoxy resin portion of LEDs with hard or sharp article such as the sand blast and the metal hook